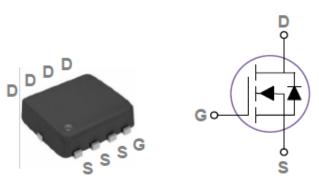




40V N-Channel MOSFETs

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications



| BVDSS | RDSON | ID |
|-------|-------|-----|
| 40V | 9mΩ | 35A |

Features

- $40V,35A,RDS(ON)=9m\Omega@VGS=10V$
- · Improved dv/dt capability
- · Fast switching
- · Green Device Available

Applications

- Networking
- · Load Switch
- · LED applications
- · Hand-Held Device

Absolute Maximum Ratings Tc=25°C unless otherwise noted

| Symbol | Parameter | Rating | Units |
|-----------------|---|------------|-------|
| V_{DS} | Drain-Source Voltage | 40 | V |
| V_{GS} | Gate-Source Voltage | ±20 | V |
| I_ | Drain Current – Continuous (TC=25°C) (Chip Limitation) | 35 | Α |
| I _D | Drain Current – Continuous (TC=100°C) (Chip Limitation) | 20 | Α |
| I _{DM} | Drain Current – Pulsed1 | 135 | Α |
| P_{D} | Power Dissipation (TC=25°C) | 40 | W |
| ' D | Power Dissipation – Derate above 25°C | 0.45 | W/°C |
| T_{STG} | Storage Temperature Range | -50 to 150 | °C |
| T _J | Operating Junction Temperature Range | -50 to 150 | °C |

Thermal Characteristics

| Symbol | Parameter | | Max. | Unit |
|-----------------|--|--|------|------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | | 65 | °C/W |
| $R_{	heta JC}$ | Thermal Resistance Junction to Case | | 3.5 | °C/W |





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Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|-----------------------------------|---|---|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V_{GS} =0V , I_D =250uA | 40 | | | V |
| $\triangle BV_{DSS}/\triangle TJ$ | BV _{DSS} Temperature Coefficient | Reference to 25°C, I _D =1mA | | 0.04 | | V/°C |
| 1 | Drain-Source Leakage Current | V_{DS} =40V , V_{GS} =0V , T_J =25°C | | | 1 | uA |
| I _{DSS} | Dialii-Source Leakage Current | V_{DS} =32V , V_{GS} =0V , T_J =125°C | | 10 | uA | |
| I _{GSS} | Gate-Source Leakage Current | V_{GS} =±20V , V_{DS} =0V | | | ±100 | nA |

On Characteristics

| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =10V , I _D =8A | | 7.5 | 9 | mΩ |
|------------------------|---|--|-----|-----|-----|-------|
| | | V_{GS} =4.5V , I_D =4A | | 11 | 14 | mΩ |
| $V_{GS(th)}$ | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 1.2 | | 2.5 | V |
| $\triangle V_{GS(th)}$ | V _{GS(th)} Temperature Coefficient | V _{GS} -V _{DS} , I _D -250uA | | -5 | | mV/°C |
| gfs | Forward Transconductance | V_{DS} =10V , I_{D} =2A | | 15 | | S |

Dynamic and switching Characteristics

| Q_g | Total Gate Charge ^{2, 3} | | 20 | 30 | |
|------------------|-------------------------------------|---|----------|------|-----|
| Q_{gs} | Gate-Source Charge ^{2, 3} | V_{DS} =20V , V_{GS} =10V , I_{D} =8A | 3.0 | 4.5 | nC |
| Q_{gd} | Gate-Drain Charge ^{2, 3} | 7 | 5.5 | 8 | |
| $T_{d(on)}$ | Turn-On Delay Time ^{2, 3} | | 13.5 | 25 | |
| T _r | Rise Time ^{2, 3} | V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω | 2.5 | 6 | ns |
| $T_{d(off)}$ | Turn-Off Delay Time ^{2, 3} | I _D =1A | 75 | 135 | 115 |
| T_f | Fall Time ^{2, 3} | | 5.0 | 13 | |
| C _{iss} | Input Capacitance | | | 2300 | |
| C _{oss} | Output Capacitance | V_{DS} =25V , V_{GS} =0V , F=1MHz | | 260 | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 120 | |
| R_g | Gate resistance | V _{GS} =0V, V _{DS} =0V, F=1MHz | 2.2 | | Ω |

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|-----------------|--------------------------------------|---|------|------|------|------|
| Is | Continuous Source Current | V _G =V _D =0V , Force Current | | | 30 | Α |
| I _{SM} | Pulsed Source Current | V _G -V _D -0V , I ofce dufferit | | | 70 | Α |
| V_{SD} | Diode Forward Voltage | V_{GS} =0V , I_{S} =1A , T_{J} =25 $^{\circ}$ C | | | 1 | V |
| trr | Reverse Recovery Time ³ | V_{GS} =0V, I_{S} =1A , dI/dt=100A/ μ s | | 18 | | ns |
| Qrr | Reverse Recovery Charge ³ | T _J =25℃ | | 3.0 | | nC |

Note:

- ${\bf 1.}\ Repetitive\ Rating: Pulsed\ width\ limited\ by\ maximum\ junction\ temperature.$
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.





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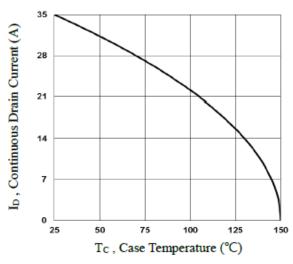


Fig.1 Continuous Drain Current vs. T_C

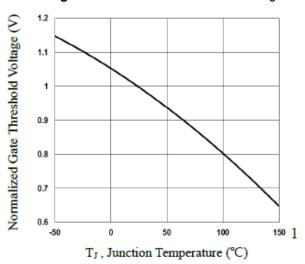


Fig.3 Normalized Vth vs. T_J

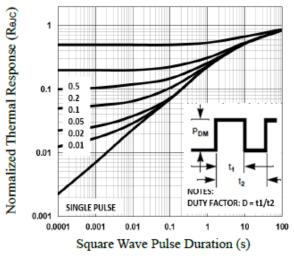


Fig.5 Normalized Transient ImpedanceIm

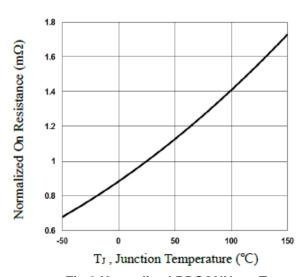


Fig.2 Normalized RDSONN vs. $T_{\rm J}$

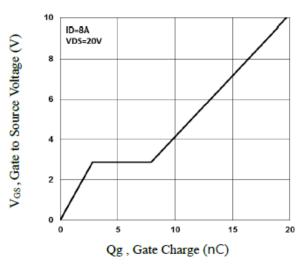


Fig.4 Gate Charge Characteristics

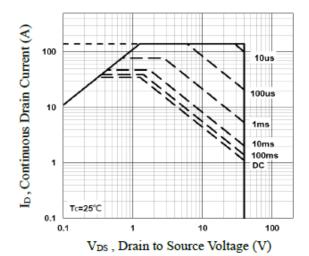


Fig.6 Maximum Safe Operation Area





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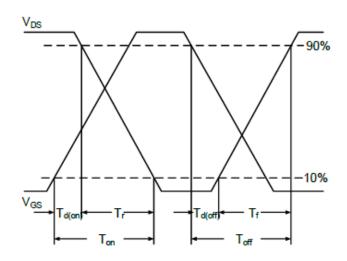


Fig.7 Switching Time Waveform

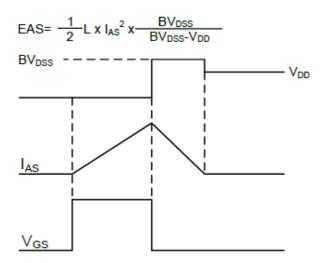
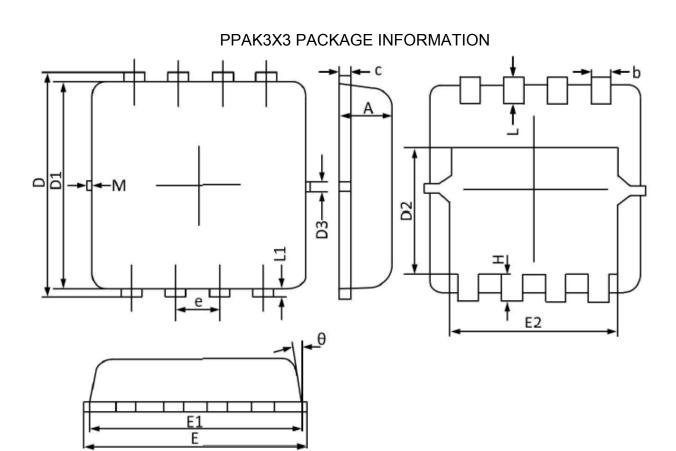


Fig.8 EAS Waveform





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| Crombal | Dimensions I | n Millimeters | Dimension | s In Inches | |
|---------|--------------|---------------|-----------|-------------|--|
| Symbol | Min | Max | Min | Max | |
| A | 0.700 | 0.800 | 0.028 | 0.031 | |
| b | 0.250 | 0.350 | 0.010 | 0.013 | |
| c | 0.100 | 0.250 | 0.004 | 0.009 | |
| D | 3.250 | 3.450 | 0.128 | 0.135 | |
| D1 | 3.000 | 3.200 | 0.119 | 0.125 | |
| D2 | 1.780 | 1.980 | 0.070 | 0.077 | |
| D3 | 0.130 | 0.130 REF | | REF | |
| E | 3.200 | 3.400 | 0.126 | 0.133 | |
| E1 | 3.000 | 3.200 | 0.119 | 0.125 | |
| E2 | 2.390 | 2.590 | 0.094 | 0.102 | |
| e | 0.650 | 0.650 BSC | | BSC | |
| Н | 0.300 | 0.500 | 0.011 | 0.019 | |
| L | 0.300 | 0.500 | 0.011 | 0.019 | |
| L1 | 0.130 | REF | 0.005 | REF | |
| θ | 0° | 12° | 0° | 12° | |
| M | 0.150 | REF | 0.006 REF | | |





40V N-Channel MOSFETs

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